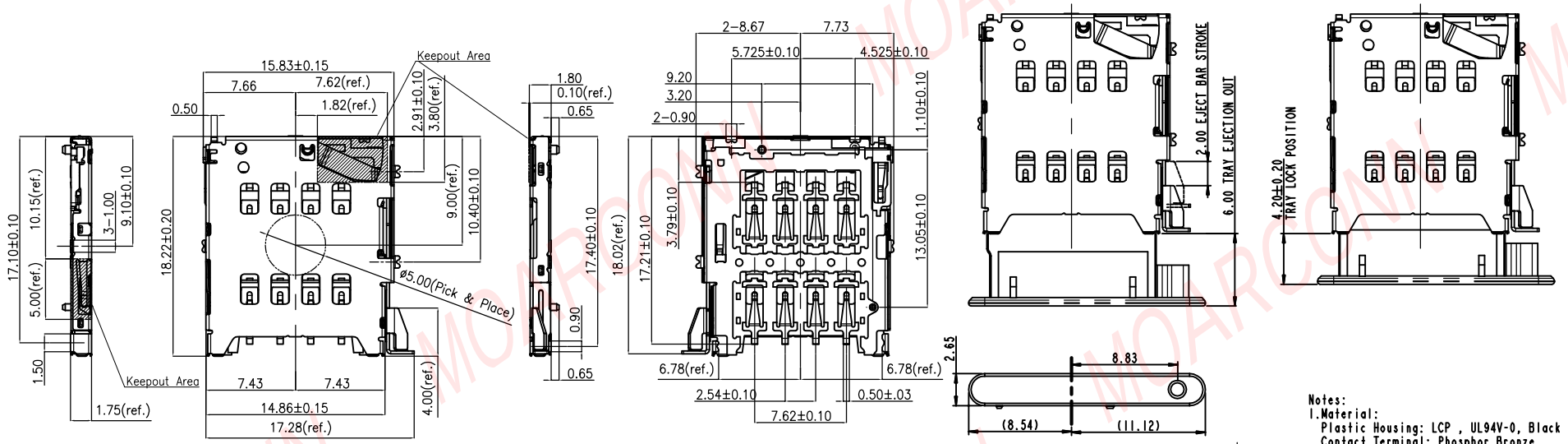
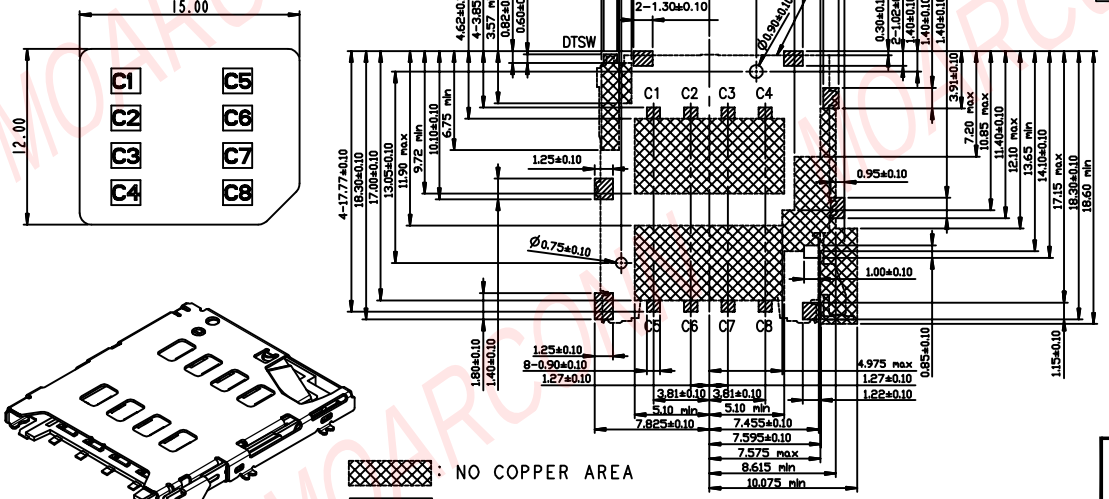
All materials, plating and process meet HF requirements.



Notes:
1.Material:
  Plastic Housing: LCP , UL94V-0, Black
  Contact Terminal: Phosphor Bronze
  Cover: SUS301, Thickness=0.15mm
2.Plating:
  Contact Terminal:
    Contact Area: Au 1U" Min .
    Solder area: Au 1U" Min.
    Underplating: Ni overall 50U" Min.
  Cover:
    Underplating: Ni overall 50U"
    Solder area: Au 1U" Min.
3.Mechanical:
  Life cycles: 5000.
4.Electrical:
  Voltage Rating: 30V AC RMS
  Current Rating: 0.5A AC RMS Max
  Operating Temperature: -20°C to +85°C
  Dielectric Withstanding Voltage: 500V AC (60Sec Min)
  Insulation Resistance: 1000MΩ Min
  Contact Resistance: 100mΩ Max
5.RECOMMENDING A METAL MORE THAN 0.15mm THICK.
  PLEASE CONFIRM SOLDERADILITY, IF USE A METAL MASK
  LESS THAN 0.15mm THICK



: NO COPPER AREA
: KEEP OUT AREA
: PAD AREA

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE±0.05
KEEP ALL OFF THE COMPONENT PROJECT AREA

	WITHOUT TRAY	TRAY MATEO
DETECTION SWITH	GND — DTSW	GND — DTSW

C1 ----> VCC
C2 ----> RST
C3 ----> CLK
C4 ----> RFU
C5 ----> GND
C6 ----> VPP
C7 ----> I/O
C8 ----> RFU

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
X1	----	NEW RELEASE	Alexander	2020.07.04

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More Connections Smart Future

DIMENSIONS INIT: mm
UNLESS OTHERWISE SPECIFIABLE

DIMENSION	TOLERANCE
x.x:	± 0.20
x.xx:	± 0.10
x.xxx:	± 0.05
ANGULAR:	± 2°

DONG GUAN MOARCONN ELECTRONIC Co., Ltd.

PRODUCT NAME : MicroSIM Eject TrayH1.8	DRAWING: Alexander	DATE: 2020.07.04	
PRODUCT NO. : MS180-T1151-01	CHECK:	DATE:	
DRAWING NO. : D-MS180-T1151-01	APPROVED:	DATE:	
	SCALE: 1:1	DWG ID: C D	REV.: X1	PAGE: 1 OF 1

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